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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

KATSUHISA MOCHIZUKI

Application No.: 10/005,697

Filed: December 7, 2001

For: FLEXIBLE WIRING FILM,
AND SEMICONDUCTOR
APPARATUS AND SYSTEM
USING THE SAME

Examiner: K. Pierre

Group Art Unit: 2822

September 5, 2002

Commissioner for Patents
Washington, D.C. 20231

RESPONSE TO OFFICE ACTION

Sir:

This is in response to the Office Action dated June 5, 2002 (Paper No. 2).

Claims 1 to 11 are pending, with Claims 1, 4, 5, 10 and 11 being independent claims.

Reconsideration and further examination are respectfully requested.

Turning first to a formal matter, it is respectfully requested for the USPTO to acknowledge receipt of the certified copy of the Japanese priority document JP 2000-380572 from which the subject application claims benefit of foreign priority under 35 U.S.C. § 119. The certified copy accompanied the Submission Of Priority Document dated August 26, 2002.

Turning to the merits of the Office Action, Claims 1 to 11 were rejected under 35 U.S.C. § 102(e) over US 2001/0048064 A1 (Kitani). The rejection is respectfully traversed.

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231 on September 5, 2002

Damond E. Vadnais (Reg. # 52,310)
Attorney for Applicant
Damond E. Vadnais September 5, 2002
Signature Date of Signature



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The invention as recited by independent Claims 1, 10 and 11 concerns a flexible wiring film comprising a lead of an electric conductor, and an insulating film. According to Claim 1, the lead has a hole in a portion exposed from the insulating film. According to Claim 10, the lead has a hole adapted to be adhered to an object. According to Claim 11, the lead has a hole which enhances adherence.

The invention as recited by independent Claim 4 concerns an apparatus which includes a lead of a flexible wiring film, a device chip electrically connected to the lead, and a sealant for sealing a connection portion between the lead and the device chip. The lead has a hole formed in a portion in contact with the sealant.

The invention as recited by independent Claim 5 concerns a semiconductor apparatus including a lead of a flexible wiring film, a semiconductor device chip electrically connected to the lead, and a protecting member for protecting a surface of the semiconductor device chip, which are sealed with a sealant in a peripheral portion of the semiconductor device chip. The lead has a hole formed in a portion in contact with the sealant.

Thus, according to one feature of the invention, the lead of the flexible wiring film has a hole. For example, in the representative embodiments shown in Figs. 1 to 5 and 9 to 10, lead 3 has a hole 6.

Kitani is not seen to teach or suggest at least this feature, where a lead contains a hole. According to Kitani, a device hole 20 is formed, in which bumps 13 and beam leads 12 are connected to each other. See col. 4, paragraphs [0065] to [0067] and Figs. 3B, 4B, 5B, and 8B of Kitani. However, Kitani is not seen to disclose that its beam lead 12 contains a hole.

This is in contrast to the present invention, in which the lead of a flexible wiring film has a hole.

In any event, Kitani is not prior art by virtue of the earlier filing date of the Japanese priority application from which the subject application claims priority under 35 U.S.C. § 119. In accordance with MPEP § 201.15, submitted herewith is a sworn translation of Japanese priority application JP 2000-380572, filed December 14, 2000. In keeping with the procedure under MPEP § 201.15, the Examiner should confirm for himself that Applicant is entitled to his priority date for the claimed subject matter. Once the Examiner is convinced that Applicant is entitled to his date, he is respectfully requested to withdraw Kitani as a reference against the pending claims.

No other matters being raised in the Office Action, it is believed that the entire application is in condition for allowance, and such action is courteously solicited.

Applicant's undersigned attorney may be reached in our Costa Mesa, California office at (714) 540-8700. All correspondence should continue to be directed to our below-listed address.

Respectfully submitted,


Attorney for Applicant

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